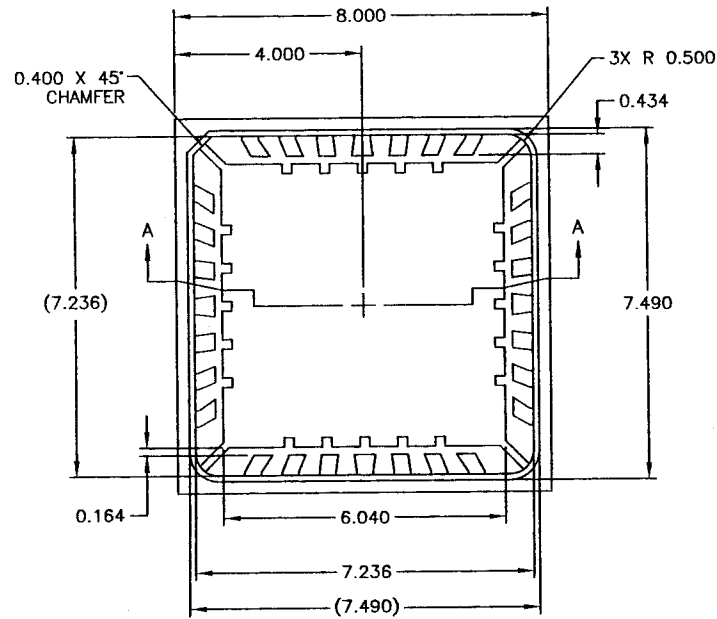
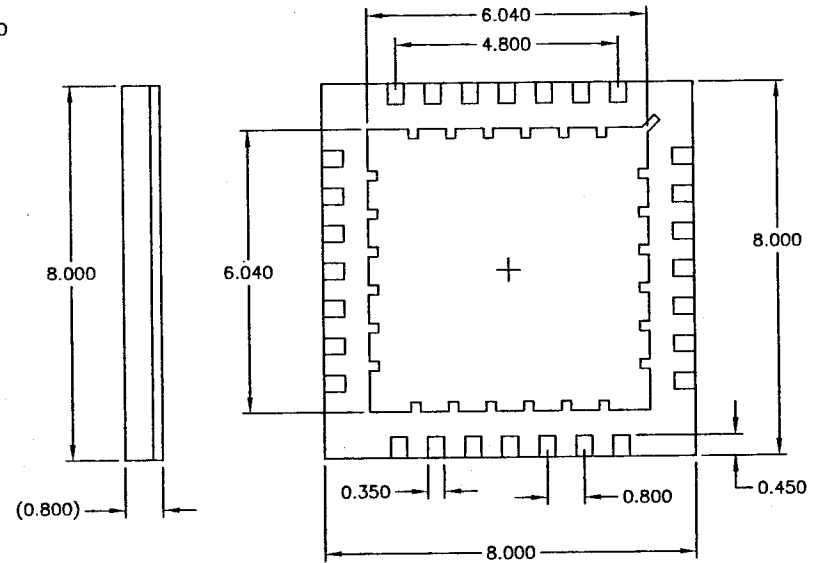


SSM P/N QFN02803

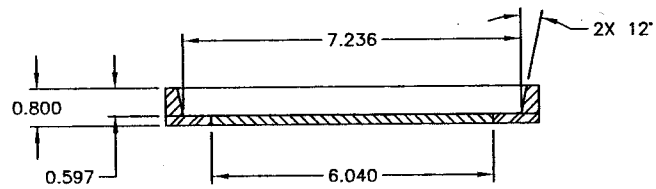
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
		PRODUCTION RELEASE	



TOP VIEW



BOTTOM VIEW



SECTION A-A

NOTES:

1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
2. LEAD FRAME: COPPER, 194 FH.
3. LEAD FINISH: FULL GOLD PLATE.
4. FRAME THICKNESS: 0.2030 ± 0.0076.
5. DIE PAD: 6.040 X 6.040.
6. JEDEC OUTLINE: MO-220 (VLLB-1).

 THIRD ANGLE PROJECTION	DRAWN BY	DATE
	APP BY	DATE
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: X.XXX ± 0.15 X.XXXX ± --- X.XXXX ± 0.100 ANGLES: ± 1° DO NOT SCALE DRAWING	CUSTOMER	

28 Lead 8mm x 8mm

QFN8X8-028 REV 1

